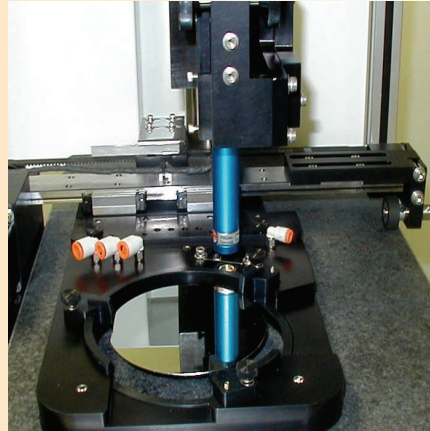
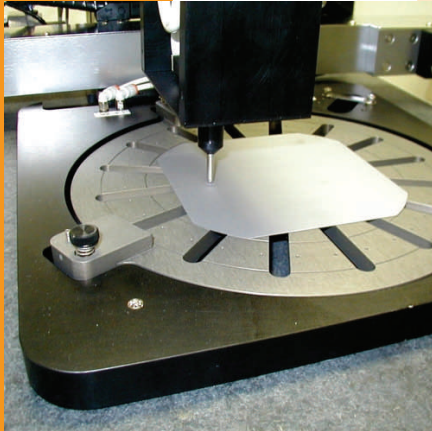


Non-Contact Dimensional Metrology

Thickness, TTV, TIR, LTV, Bow, Warp, SORI, FPD, flatness



Sigmattech UltraMapA-300: White light chromatic coding probes

Wafers 4" to 12", Cassette to cassette or manual loading.
Full SECS/GEM compatible

Applications: High volume wafer production control, backgrinding control, Wafer characterization, extreme warp wafers, ultrathin wafers

Sigmattech UltraMapA-100: Benchtop model: White light chromatic coding probes

Wafers 2" to 4", Cassette to cassette or manual loading

Applications: Small wafers production control, SiC, Sapphire, Glass, InP

Sigmattech 9600S-IR-300: IR interferometry probe technology,

Wafers 4" to 12". Manual loading

Applications: wafers on sawframe, SOI, multilayers

Sigmattech 9600A: APBP (backpressure probe technology)

Wafer 4" to 12", Cassette to cassette or manual loading, SECS/GEM

Applications: All non-silicon wafers, ceramics, glass, sapphire, non-controlled environments

Sigmattech 9600M: APBP (backpressure probe technology)

Manual system for wafer 2" to 12"

Applications: Wafer thickness QA and R&D labs. All material, all surface
Ultrathin material from 20um to 5mm

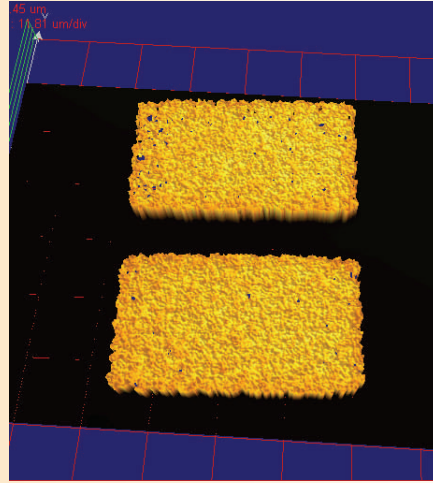
SigmaTech customized systems: For non-standard applications.

Metrology solutions with combined sensing technologies available

Product Summary

Surface Metrology & Inspection

MEMS, Bumps, sub-nanometric roughness, cavity, solder ball, steps



Sigmattech UltraSurf™ serie: Non-contact Optical profilers

White light and phase-shifting interferometry, non-contact 3D scanning

Sigmattech UltraSurf™ M:

Compact microscope for sub-nanometric measurement. Powerful analysis software. 500um range

Applications: R&D labs, Step height, bump size, Roughness, surface topography

Sigmattech UltraSurf™ P:

Interferometric sensor for fast 3D measurement, up to 200mm sample handling capabilities, Powerful analysis software.

Applications: Bump size, step height, film thickness, surface topography, roughness, MEMS (vibration analysis)

Sigmattech UltraSurf™ SZ:

Fully automated optical profiling system for sub-nanometric measurement. Powerful analysis software.

Applications: R&D labs and production environment. Step height, bump size, Roughness, surface topography, field stitching

Sigmattech UltraSurf™ A3D:

Fully automated wafer process control.

Cassette to cassette or manual loading. 6", 8" and 12" wafers
Auto wafer alignment

Applications: production control. Step height, bump size, Roughness, surface topography, pattern dimension, transparent film and Photoresist thickness mapping